

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C1	1	1000pF	CAP, CERM, 1000pF, 100V, +/-5%, C0G/NP0, 0805	0805	GRM2195C2A102JA01D	MuRata
C2, C3, C16, C17	4	3.3uF	CAP, CERM, 3.3uF, 50V, +/-10%, X7R, 1210	1210	GRM32DR71H335KA88L	MuRata
C4, C18	2	10uF	CAP, CERM, 10uF, 100V, [TempCo], xx%, [PackageReference]	Used in PnP output	Used in BOM report	Used in BOM report
C5, C19	2	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Used in PnP output	Used in BOM report	Used in BOM report
C6, C20	2	0.1uF	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	0603	C0603C104K3RACTU	Kemet
C7, C9, C21, C23	4	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603	GRM1885C1H101JA01D	MuRata
C8, C22	2	4.7uF	CAP, CERM, 4.7uF, 16V, +/-10%, X7R, 0805	0805	GRM21BR71C475KA73L	MuRata
C10, C24	2	0.47uF	CAP, CERM, 0.47uF, 50V, +/-10%, X7R, 0805	0805	GRM21BR71H474KA88L	MuRata
C11, C25	2	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603	GRM188R71E105KA12D	MuRata
C12, C26	2	47pF	CAP, CERM, 47pF, 50V, +/-5%, C0G/NP0, 0603	0603	C0603C470J5GACTU	Kemet
C13, C27	2	NA	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Used in PnP output	Used in BOM report	Used in BOM report
C14	1	820pF	CAP, CERM, 820pF, 50V, +/-5%, C0G/NP0, 0603	0603	C0603C821J5GACTU	Kemet
C15	1	6800pF	CAP, CERM, 6800pF, 100V, +/-10%, X7R, 0805	0805	GRM219R72A682KA01D	MuRata
C28	1	820pF	CAP, CERM, 820pF, 50V, +/-10%, X7R, 0603	0603	C0603C821K5RACTU	Kemet
C101	1	TBD	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output	Used in BOM report	Used in BOM report
C102	1	3.9mF	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output	Used in BOM report	Used in BOM report
C201	1	2.7mF	CAP, [Technology], xxxF, xxV, +/-xx%, xxOhm ESR, [MountType]	Used in PnP output	Used in BOM report	Used in BOM report
D1, D2	2	0.57V	Diode, Schottky, 60V, 1A, SOD-123F	SOD-123F	PMEG6010CEH,115	NXP Semiconductor
L1, L2	2	22u	Inductor, [Technology], [Material], xxuH, xxA, x.xx ohm, [MountType]	Used in PnP output	XAL1510	Used in BOM report
Q1, Q2, Q3, Q4, Q5, Q6	6	80V	MOSFET, N-CH, 80V, 45A, DDPAK	DDPAK	IPB097N08N3	Infineon Technologies
R1, R19	2	0.005	RES, xxx ohm, x%, xW, [PackageReference]	Used in PnP output	Used in BOM report	Used in BOM report
R2	1	8.2	RES 8.2 OHM 3/4W 5% 2010 SMD	2010 (5025 Metric)	CRCW20108R20JNEF	Vishay Dale
R3, R4, R21, R22	4	100	RES, 100 ohm, 1%, 0.1W, 0603	0603	CRCW0603100RFKEA	Vishay-Dale
R5, R6, R7, R23, R24, R25	6	0	RES, 0 ohm, 5%, 0.125W, 0805	0805	CRCW08050000Z0EA	Vishay-Dale
R8, R26	2	0	RES, 0 ohm, 5%, 0.1W, 0603	0603	ERJ-3GEY0R00V	Panasonic
R9, R27	2	49.9k	RES, 49.9k ohm, 1%, 0.1W, 0603	0603	CRCW060349K9FKEA	Vishay-Dale
R10, R28	2	3.3	RES, 3.3 ohm, 5%, 0.1W, 0603	0603	CRCW06033R30JNEA	Vishay-Dale
R11, R29	2	12.1k	RES, 12.1k ohm, 1%, 0.1W, 0603	0603	CRCW060312K1FKEA	Vishay-Dale
R12, R30	2	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale
R13	1	75k	RES, 75k ohm, 5%, 0.1W, 0603	0603	CRCW060375K0JNEA	Vishay-Dale
R14, R31	2	NA	RES, xxx ohm, x%, xW, [PackageReference]	Used in PnP output	Used in BOM report	Used in BOM report
R15, R32	2	249k	RES, 249k ohm, 1%, 0.1W, 0603	0603	CRCW0603249KFKEA	Vishay-Dale
R16, R33	2	604	RES, 604 ohm, 1%, 0.1W, 0603	0603	CRCW0603604RFKEA	Vishay-Dale
R17, R34	2	24.9k	RES, 24.9k ohm, 1%, 0.1W, 0603	0603	CRCW060324K9FKEA	Vishay-Dale
R18, R35	2	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale
R20, R101	2	2.2	RES, 2.2 ohm, 5%, 1W, 2010	2010	CRM2010-JW-2R2ELF	Bourns
TP1, TP7, TP8, TP9, TP10, TP15, TP16	7	Red	Test Point, TH, Miniature, Red	Keystone5000	5000	Keystone
TP2, TP3, TP4, TP5, TP12, TP13	6	Double	Terminal, Turret, TH, Double	Keystone1503-2	1503-2	Keystone
TP6, TP11, TP14	3	Black	Test Point, TH, Miniature, Black	Keystone5001	5001	Keystone
U1, U2	2			MXA20A	LM5122MH	TI

Notes:

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